#### **FEATURES:**

- · Phase-Lock Loop Clock Distribution
- 10MHz to 133MHz operating frequency
- · Distributes one clock input to one bank of five outputs
- Zero Input-Output Delay
- Output Skew < 250ps
- Low jitter <175 ps cycle-to-cycle</li>
- 50ps typical cycle-to-cycle jitter (15pF, 66MHz)
- · IDT2305B-1 for Standard Drive
- IDT2305B-1H for High Drive
- · No external RC network required
- Operates at 3.3V VDD
- · Power down mode
- · Available in SOIC and TSSOP packages

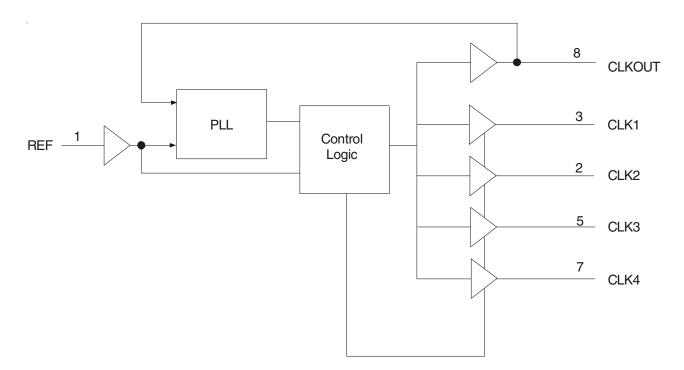
#### **DESCRIPTION:**

The IDT2305B is a high-speed phase-lock loop (PLL) clock buffer, designed to address high-speed clock distribution applications. The zero delay is achieved by aligning the phase between the incoming clock and the output clock, operable within the range of 10 to 133MHz.

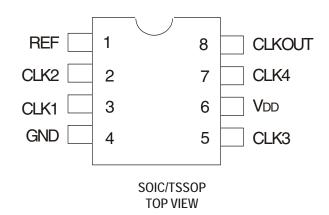
The IDT2305B is an 8-pin version of the IDT2309B. IDT2305B accepts one reference input, and drives out five low skew clocks. The -1H version of this device operates, up to 133MHz frequency and has a higher drive than the -1 device. All parts have on-chip PLLs which lock to an input clock on the REF pin. The PLL feedback is on-chip and is obtained from the CLKOUT pad. In the absence of an input clock, the IDT2305B enters power down. In this mode, the device will draw less than  $25\mu\text{A}$ , the outputs are tri-stated, and the PLL is not running, resulting in a significant reduction of power.

The IDT2305B is characterized for both Industrial and Commercial operation.

#### **FUNCTIONAL BLOCK DIAGRAM**



#### **PINCONFIGURATION**



#### **APPLICATIONS:**

- SDRAM
- Telecom
- Datacom
- PC Motherboards/Workstations
- Critical Path Delay Designs

## ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Max.	Unit
VDD	Supply Voltage Range	-0.5 to +4.6	V
VI <sup>(2)</sup>	Input Voltage Range (REF)	-0.5 to +5.5	V
Vı	Input Voltage Range	-0.5 to	V
	(except REF)	VDD+0.5	
IIK (VI < 0)	Input Clamp Current	<b>-</b> 50	mA
Io (Vo = 0 to VDD)	Continuous Output Current	±50	mA
VDD or GND	Continuous Current	±100	mA
TA = 55°C	Maximum Power Dissipation	0.7	W
(in still air)(3)			
Tstg	Storage Temperature Range	-65 to +150	°C
Operating	Commercial Temperature	0 to +70	°C
Temperature	Range		
Operating	Industrial Temperature	-40 to +85	°C
Temperature	Range		

#### NOTES:

- 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

#### **PINDESCRIPTION**

Pin Name	Pin Number	Туре	Functional Description
REF	1	IN	Input reference clock, 5 Volt tolerant input
CLK2 <sup>(1)</sup>	2	Out	Output clock
CLK1 <sup>(1)</sup>	3	Out	Output clock
GND	4	Ground	Ground
CLK3 <sup>(1)</sup>	5	Out	Output clock
VDD	6	PWR	3.3V Supply
CLK4 <sup>(1)</sup>	7	Out	Output clock
CLKOUT <sup>(1)</sup>	8	Out	Output clock, internal feedback on this pin

#### NOTES:

1. Weak pull down on all outputs.

## **OPERATING CONDITIONS-COMMERCIAL**

Symbol	Parameter	Min.	Max.	Unit
VDD	Supply Voltage	3	3.6	V
TA	Operating Temperature (Ambient Temperature)	0	70	°C
CL	Load Capacitance < 100MHz	_	30	pF
	Load Capacitance 100MHz - 133MHz	_	10	
CIN	Input Capacitance	_	7	pF

### DC ELECTRICAL CHARACTERISTICS-COMMERCIAL

Symbol	Parameter	C	onditions	Min.	Max.	Unit
VIL	Input LOW Voltage Level			_	0.8	V
VIH	Input HIGH Voltage Level			2	_	V
lıL	Input LOW Current	VIN = 0V		_	50	μΑ
Iн	Input HIGH Current	VIN = VDD	VIN = VDD		100	μΑ
Vol	Output LOW Voltage	Standard Drive	IoL = 8mA	_	0.4	V
		High Drive	IoL = 12mA (-1H)			
Voн	Output HIGH Voltage	Standard Drive	Iон = -8mA	2.4		
		High Drive	Iон = -12mA (-1H)			
IDD_PD	Power Down Current	REF = 0MHz		_	12	μΑ
IDD	Supply Current	Unloaded Outputs at 66.	Unloaded Outputs at 66.66MHz		32	mA

# SWITCHING CHARACTERISTICS (2305B-1)-COMMERCIAL (1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
t1	Output Frequency	10pFLoad	10	_	133	MHz
		30pFLoad	10	_	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, Fout = 66.66MHz	40	50	60	%
t3	Rise Time	Measured between 0.8V and 2V	_	_	2.5	ns
<b>t</b> 4	FallTime	Measured between 0.8V and 2V	_	_	2.5	ns
t5	Output to Output Skew	All outputs equally loaded	_	_	250	ps
t6	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	_	0	±350	ps
t7	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
tJ	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	50	175	ps
tLOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

- 1. REF Input has a threshold voltage of VDD/2.
- 2. All parameters specified with loaded outputs.

# SWITCHING CHARACTERISTICS (2305B-1H)-COMMERCIAL (1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
t1	Output Frequency	10pFLoad	10	_	133	MHz
		30pF Load	10	_	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, Fout = 66.66MHz	40	50	60	%
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, Fout <50MHz	45	50	55	%
t3	Rise Time	Measured between 0.8V and 2V		_	1.5	ns
t4	Fall Time	Measured between 0.8V and 2V	_	_	1.5	ns
t5	Output to Output Skew	All outputs equally loaded	_	_	250	ps
t6	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	_	0	±350	ps
t7	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
t8	Output Slew Rate	Measured between 0.8V and 2V using Test Circuit #2	1	_	_	V/ns
tu	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	_	175	ps
tLOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

#### NOTES:

- 1. REF Input has a threshold voltage of VDD/2.
- 2. All parameters specified with loaded outputs.

## **OPERATING CONDITIONS-INDUSTRIAL**

Symbol	Parameter	Min.	Max.	Unit
Vdd	Supply Voltage	3	3.6	V
TA	Operating Temperature (Ambient Temperature)	-40	+85	°C
CL	Load Capacitance < 100MHz	_	30	pF
	Load Capacitance 100MHz - 133MHz	_	10	
Cin	Input Capacitance	_	7	pF

### DC ELECTRICAL CHARACTERISTICS-INDUSTRIAL

Symbol	Parameter	C	Conditions	Min.	Max.	Unit
VIL	Input LOW Voltage Level			_	0.8	V
VIH	Input HIGH Voltage Level			2	_	V
lıL	Input LOW Current	VIN = 0V		_	50	μA
lін	Input HIGH Current	VIN = VDD	VIN = VDD		100	μA
Vol	Output LOW Voltage	Standard Drive	IoL = 8mA	_	0.4	V
		High Drive	IoL = 12mA (-1H)			
Voн	Output HIGH Voltage	Standard Drive	Iон = -8mA	2.4	_	V
		High Drive	Iон = -12mA (-1H)			
IDD_PD	Power Down Current	REF = 0MHz		_	25	μΑ
IDD	Supply Current	Unloaded Outputs at 66.	66MHz	_	35	mA

# SWITCHING CHARACTERISTICS (2305B-1)-INDUSTRIAL (1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pFLoad	10	_	133	MHz
		30pFLoad	10	_	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
t3	Rise Time	Measured between 0.8V and 2V	_	_	2.5	ns
t4	FallTime	Measured between 0.8V and 2V		_	2.5	ns
t5	Output to Output Skew	All outputs equally loaded	_	_	250	ps
t6	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	_	0	±350	ps
tr	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
tu	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	50	175	ps
tlock	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

#### NOTES:

- 1. REF Input has a threshold voltage of VDD/2.
- 2. All parameters specified with loaded outputs.

## SWITCHING CHARACTERISTICS (2305B-1H) - INDUSTRIAL (1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pFLoad	10	_	133	MHz
		30pFLoad	10	_	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, Fout = 66.66MHz	40	50	60	%
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, Fout <50MHz	45	50	55	%
t3	Rise Time	Measured between 0.8V and 2V	_	_	1.5	ns
t4	Fall Time	Measured between 0.8V and 2V	_	_	1.5	ns
t5	Output to Output Skew	All outputs equally loaded		_	250	ps
t6	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	_	0	±350	ps
t	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
t8	Output Slew Rate	Measured between 0.8V and 2V using Test Circuit #2	1	_	_	V/ns
tu	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	_	175	ps
tLOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

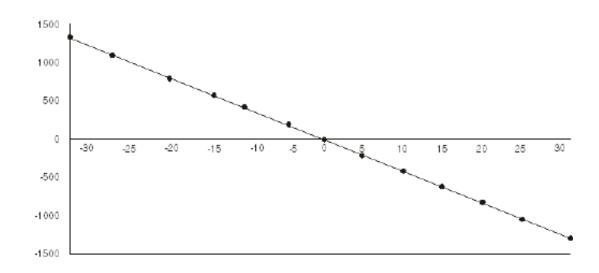
- 1. REF Input has a threshold voltage of VDD/2.
- 2. All parameters specified with loaded outputs.

#### ZERO DELAY AND SKEW CONTROL

All outputs should be uniformly loaded in order to achieve Zero I/O Delay. Since the CLKOUT pin is the internal feedback for the PLL, its relative loading can affect and adjust the input/output delay. The Output Load Difference diagram illustrates the PLL's relative loading with respect to the other outputs that can adjust the Input-Output (I/O) Delay.

For designs utilizing zero I/O Delay, all outputs including CLKOUT must be equally loaded. Even if the output is not used, it must have a capacitive load equal to that on the other outputs in order to obtain true zero I/O Delay. If I/O Delay adjustments are needed, use the Output Load Difference diagram to calculate loading differences between the CLKOUT pin and other outputs. For zero output-to-output skew, all outputs must be loaded equally.

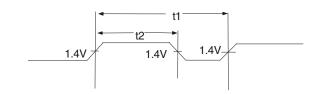
#### REF TO CLKA/CLKB RELAY vs. OUTPUT LOAD DIFFERENCE BETWEEN CLKOUT PIN AND CLKA/CLKB PINS



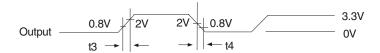
OUTPUT LOAD DIFFERENCE BETWEEN CLKOUT PIN AND CLKA/CLKB PINS (pF)

REF to CLKA/CLKB Delay (ps)

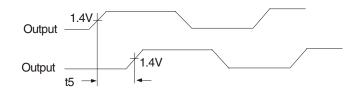
## **SWITCHING WAVEFORMS**



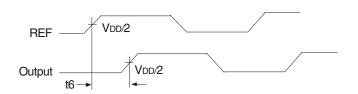
Duty Cycle Timing



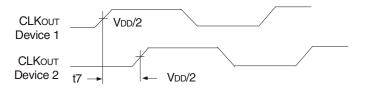
All Outputs Rise/Fall Time



Output to Output Skew

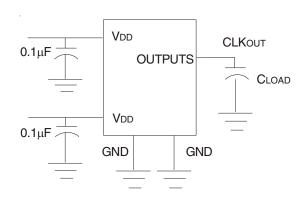


Input to Output Propagation Delay



Device to Device Skew

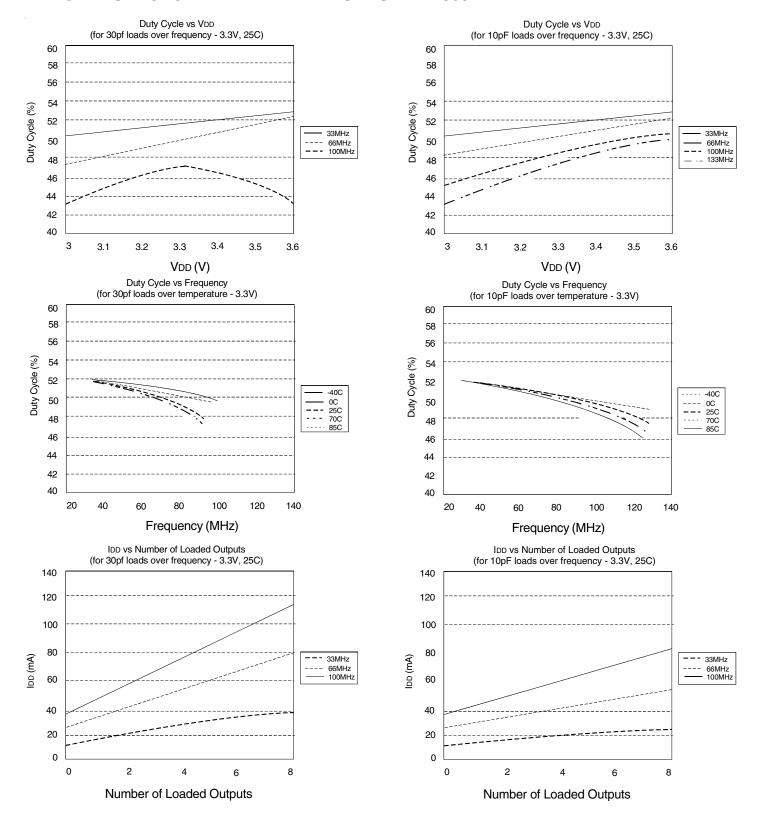
## **TEST CIRCUITS**



Test Circuit 1 (all Parameters Except t8)

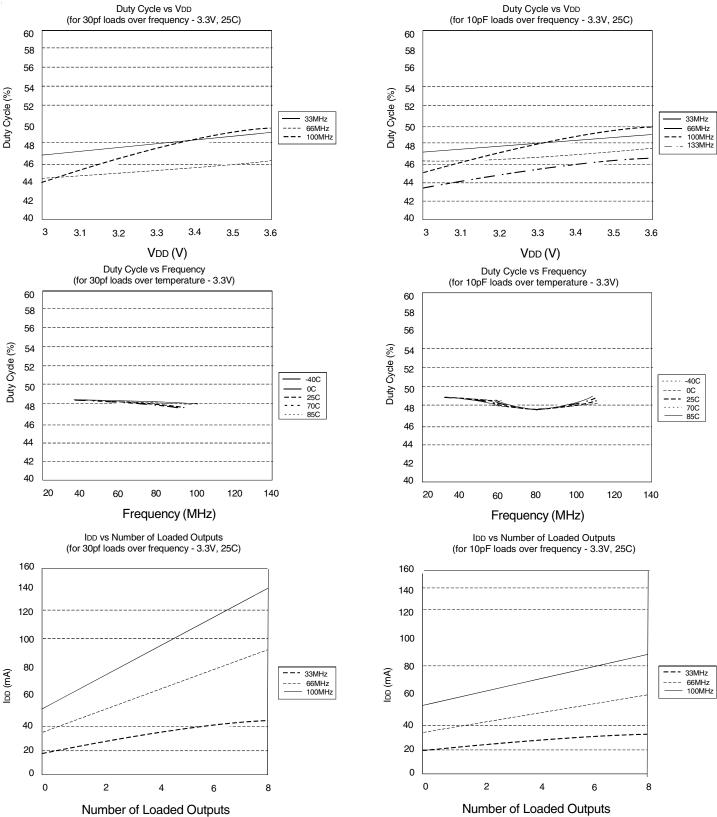
Test Circuit 2 (t8, Output Slew Rate On -1H Devices)

### TYPICAL DUTY CYCLE(1) AND IDD TRENDS(2) FOR IDT2305B-1



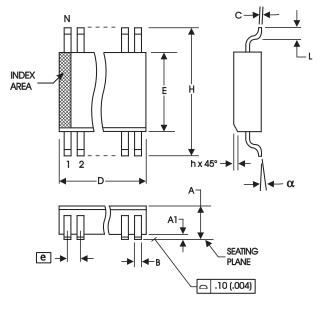
- 1. Duty Cycle is taken from typical chip measured at 1.4V.
- 2. IDD data is calculated from IDD = ICORE + nCVf, where ICORE is the unloaded current. (n = Number of outputs; C = Capacitance load per output (F); V = Supply Voltage (V); f = Frequency (Hz))

### TYPICAL DUTY CYCLE(1) AND IDD TRENDS(2) FOR IDT2305B-1H



- 1. Duty Cycle is taken from typical chip measured at 1.4V.
- IDD data is calculated from IDD = ICORE + nCVf, where ICORE is the unloaded current. (n = Number of outputs; C = Capacitance load per output (F); V = Supply Voltage (V); f = Frequency (Hz))

## 8-Pin SOIC Package Drawing and Dimensions



150 mil (Narrow Body) SOIC

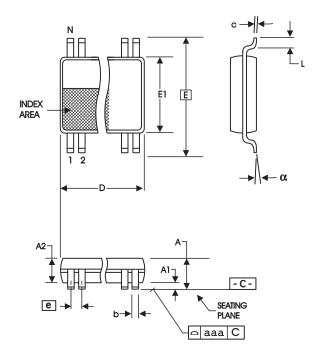
	150 mil (Narrow Body) SOIC							
	In Milli	meters	In Inches					
SYMBOL	COMMON D	IMENSIONS	COMMON E	IMENSIONS				
	MIN	MAX	MIN	MAX				
Α	1.35	1.75	.0532	.0688				
A1	0.10	0.25	.0040	.0098				
В	0.33	0.51	.013	.020				
С	0.19	0.25	.0075	.0098				
D	SEE VAR	RIATIONS	SEE VARIATIONS					
E	3.80	4.00	.1497	.1574				
е	1.27 E	BASIC	0.050	BASIC				
Н	5.80	6.20	.2284	.2440				
h	0.25	0.50	.010	.020				
L	0.40	1.27	.016	.050				
N	SEE VAR	RIATIONS	SEE VARIATIONS					
α	٥°	8°	٥°	8°				

#### **VARIATIONS**

N	D mm.		D (inch)	
N	MIN	MAX	MIN	MAX
8	4.80	5.00	.1890	.1968

Reference Doc.: JEDEC Publication 95, MS-012 10-0030

## 8-Pin TSSOP Package Drawing and Dimensions



4.40 mm. Body, 0.65 mm. Pitch TSSOP

	(173 mil)	(25.6 mil)		
	In Millimeters		In Inches	
SYMBOL	COMMON DIMENSIONS		COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
Α		1.20		.047
A1	0.05	0.15	.002	.006
A2	0.80	1.05	.032	.041
b	0.19	0.30	.007	.012
С	0.09	0.20	.0035	.008
D	SEE VARIATIONS		SEE VARIATIONS	
E	6.40 BASIC		0.252 BASIC	
E1	4.30	4.50	.169	.177
е	0.65 BASIC		0.0256 BASIC	
L	0.45	0.75	.018	.030
N	SEE VARIATIONS		SEE VARIATIONS	
а	0°	8°	0°	8°
222		0.10		004

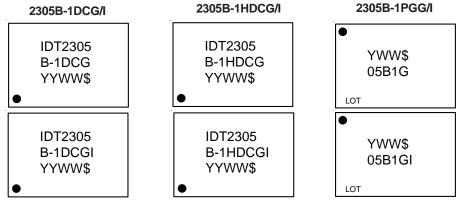
#### **VARIATIONS**

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
8	2.90	3.10	.114	.122

Reference Doc.: JEDEC Publication 95, MO-153

10-0035

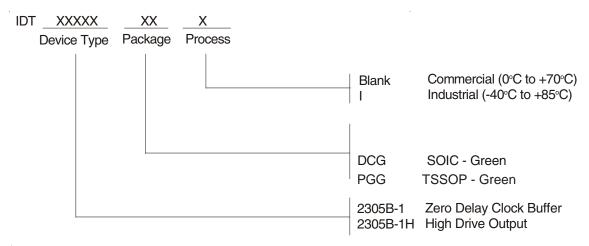
#### **MARKING DIAGRAMS**



#### Notes:

- 1. "G" denotes Pb-free (green)
- 2. "YYWW" or "YWW" is the last digit(s) of the year and week that the part was assembled.
- 3. "I" denotes industrial temperature grade.
- 4. "\$" denotes mark code.
- 5. "LOT" denotes lot number.

## **ORDERING INFORMATION**



Ordering Code	Package Type	Operating Range
2305B-1DCG8 (tape and reel)	8-Pin SOIC	Commercial
2305B-1DCG	8-Pin SOIC	Commercial
2305B-1DCGI8 (tape and reel)	8-Pin SOIC	Industrial
2305B-1DCGI	8-Pin SOIC	Industrial
2305B-1HDCG8 (tape and reel)	8-Pin SOIC	Commercial
2305B-1HDCG	8-Pin SOIC	Commercial
2305B-1HDCGI8 (tape and reel)	8-Pin SOIC	Industrial
2305B-1HDCGI	8-Pin SOIC	Industrial
2305B-1PGG8 (tape and reel)	8-Pin TSSOP	Commercial
2305B-1PGG	8-Pin TSSOP	Commercial
2305B-1PGGI8 (tape and reel)	8-Pin TSSOP	Industrial
2305B-1PGGI	8-Pin TSSOP	Industrial

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PI6C4931502-04LIE NB7L1008MNG NB7L14MN1G PI49FCT20807QE PI6C4931502-04LIEX ZL80002QAB1 PI6C4931504-04LIEX

PI6C10806BLEX ZL40226LDG1 ZL40219LDG1 8T73S208B-01NLGI SY75578LMG PI49FCT32805QEX PL133-27GC-R

CDCV304PWG4 MC10LVEP11DG MC10EP11DTG MC100LVEP11DG MC100E111FNG MC100EP11DTG NB6N11SMNG

NB7L14MMNG NB6L11MMNG NB6L14MMNR2G NB6L611MNG PL123-02NGI-R NB3N111KMNR4G ADCLK944BCPZ-R7

ZL40217LDG1 NB7LQ572MNG HMC940LC4BTR ADCLK946BCPZ-REEL7 ADCLK946BCPZ ADCLK846BCPZ-REEL7

ADCLK854BCPZ-REEL7